PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	ADG/21/13162
1.3 Title of PCI	Better bonding sequence layout
1.4 Product Category	SiC MOSFET
1.5 Issue date	2021-12-09

2. PCI Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio Maria FERRARA
2.1.2 Marketing Manager	Michele MACAUDA
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process adjustment within specification limits when no reliability or quality risk has been highlighted by the risk assessment.	SHZ China

4. Description of change

	Old	New
4.1 Description	Bonding sequence: long wire->short wire-> long wire -> short wire	New bonding sequence : long wire-> long wire-> short wire -> short wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change	
5.1 Motivation	Better bonding layout for yield improvement and higher throughput
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	by Q.A. number

7. Timing / schedule	
7.1 Date of qualification results	2021-12-07
7.2 Intended start of delivery	2022-01-10
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

13162 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SCTW70N120G2V	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Better bonding sequence layout
PCI Reference : ADG/21/13162

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SCTW100N120G2AG	SCTW70N120G2V	

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